

Dow Electronic Materials to Showcase Leading Materials for Printed Circuit Board Manufacturing at the IPC APEX EXPO

*Collaborative development key to meeting customer requirements;
Products offer reliability, consistency and reduced costs for PCBs*

MARLBOROUGH, Mass.—April 6, 2011—[Dow Electronic Materials](#) will showcase its innovative materials for printed circuit boards (PCBs) at this year's IPC APEX EXPO. Dow will feature a number of its latest products that are tailored to meet the requirements of increasingly complex circuit boards while delivering ever-higher reliability and consistency. Dow's next-generation of high quality, cost-effective technologies allow customers to meet future market requirements.

"Dow brings to the PCB market not only the latest and most advanced products, but also an industry-leading understanding of technology and manufacturing requirements," said Helen Zhang, Global General Manager for Dow Electronic Materials. "This expertise, along with our extensive global footprint, is critical to our ability to work with our customers so they can achieve high yield and performance in their manufacturing processes. Our metallization technologies and the service we deliver with our products allow us to support a broad array of markets including telecom, military, aerospace, medical and photovoltaic."

At the IPC APEX EXPO, Dow will highlight two products for PCB final finish, in which the coating layer is created on the conductive pad surface to provide solderability, wire bonding and protection. A third product featured targets PCB electrolytic plating.

First, AUROLECTROLESS™ SMT 520 Immersion Gold Bath can substantially reduce operating costs with its low gold salt content (0.5g/L – 0.74g/L) without sacrificing performance. Producing uniform, fine-grained deposits of pure gold on metallic substrates, the bath is easy to control, has high tolerance to contaminants, and offers consistent performance over the bath life. AUROLECTROLESS™ SMT 520 Immersion Gold Bath provides excellent deposit coverage to increase corrosion resistance during subsequent process steps and is suitable for both electroless nickel immersion gold (ENIG) and electroless nickel electroless palladium immersion gold (ENEPIG) applications.

Second, SILVERON™ MF 100 Electroless Silver is an innovative autocatalytic silver material composed of silver with anti-tarnish allowing it to achieve the performance capability of ENIG without the corrosion and ground plating associated with nickel. Offering a dense silver coating that prevents diffusion of copper to the silver surface to reduce the formation of copper oxide, SILVERON™ MF 100 Electroless Silver delivers strong solder joints, multiple reflow capabilities, excellent wire bonding capability and exceptional RF performance when compared to nickel.

The company's third featured product at the show is MICROFILL™ EVF Copper Via Fill targeting PCB electrolytic plating. Providing enhanced via filling at exceptionally low surface thicknesses, MICROFILL™ EVF Copper Via Fill is capable of simultaneous through-hole plating. Suitable for both high density interconnect (HDI) and integrated circuit (IC) substrate applications, it is compatible with both panel and pattern plating processing as well as soluble and insoluble anodes. MICROFILL™ EVF Copper Via Fill products are easily analyzed to deliver excellent reliability.

Other products to be featured include LITHOJET™ Products for primary imaging, CIRCUPOSIT™ 7800 Products for desmear and electroless copper applications in the packaging substrate industry and ENLIGHT™ Products including metallization and imaging offerings for the photovoltaic manufacturing process.

Dow Electronic Materials will be exhibiting in Booth #1249 at the IPC APEX EXPO, which will be held at the Mandalay Bay Resort & Convention Center in Las Vegas, Nevada, USA, from April 12 to 14, 2011.

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About Dow

Dow (NYSE: Dow) combines the power of science and technology with the “Human Element” to passionately innovate what is essential to human progress. The Company connects chemistry and innovation with the principles of sustainability to help address many of the world’s most challenging problems such as the need for clean water, renewable energy generation and conservation, and increasing agricultural productivity. Dow’s diversified industry-leading portfolio of specialty chemical, advanced materials, agrosiences and plastics businesses delivers a broad range of technology-based products and solutions to customers in approximately 160 countries and in high growth sectors such as electronics, water, energy, coatings and agriculture. In 2010, Dow had annual sales of \$53.7 billion and employed approximately 50,000 people worldwide. The Company’s more than 5,000 products are manufactured at 188 sites in 35 countries across the globe. References to "Dow" or the "Company" mean The Dow Chemical Company and its consolidated subsidiaries unless otherwise expressly noted. More information about Dow can be found at www.dow.com.

About Dow Electronic Materials

Dow Electronic Materials, a global supplier of materials and technologies to the electronics industry, brings innovative leadership to the semiconductor, interconnect, finishing, photovoltaic, display, LED and optics markets. From advanced technology centers worldwide, teams of talented Dow research scientists and application experts work closely with customers, providing solutions, products and technical service necessary for next-generation electronics. These partnerships energize Dow’s power to invent. Its key end-use applications include a broad range of consumer electronics from personal computers, to television monitors, cellular phones, global positioning systems, automobile safety systems, and avionics.

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